SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

- 3-State Outputs Drive Bus Lines Directly
- Encodes 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:

 N-Bit Encoding
 Code Converters and Generators
- Typical Data Delay . . . 15 ns
- Typical Power Dissipation . . . 60 mW

description

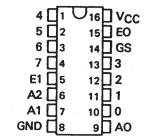
These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The 'LS348 circuits encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input E1 and enable output E0) has been provided to allow octal expansion. Outputs A0, A1, and A2 are implemented in three-state logic for easy expansion up to 64 lines without the need for external circuitry. See Typical Application Data.

FUNCTION TABLE

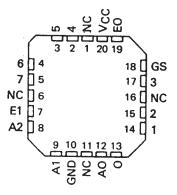
	INPUTS									Ol	JTPU	TS	
EI	0	1	2	3	4	5	6	7	A2	A1	A0	GS	EO
Н	Х	Х	Χ	Х	Χ	X	X	Х	Z	Z	Z	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	z	Z	Z	н	L
L	Х	Х	Х	Х	Х	Χ	Х	L	L	L	L	L	н
L	Х	Х	X	Х	Х	Х	L	Н	L	L	Н	L	н
L	Х	Х	Χ	X	Х	L	Н	Н	L	Н	L	L	н
L	Х	Х	Χ	Х	L	Н	Н	Н	L	Н	Н	L	н
L	Ý	Х	Х	L	Н	Н	Н	Н	н	L	L	L	н
L	Х	Х	L	Н	Н	Н	Н	Н	н	L	н	L	н
L	X	L	Н	H	Н	Н	Н	Н	н	Н	L	L	н
L	L	Н	Н	Н	H	Н	Н	Н	Н	Н	Н	L	н

H = high logic level, L = low logic level, X = irrelevant

SN54LS348 . . . J OR W PACKAGE SN74LS348 . . . D OR N PACKAGE (TOP VIEW)

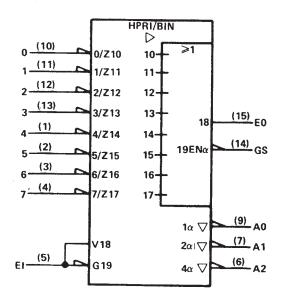


SN54LS348 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol[†]



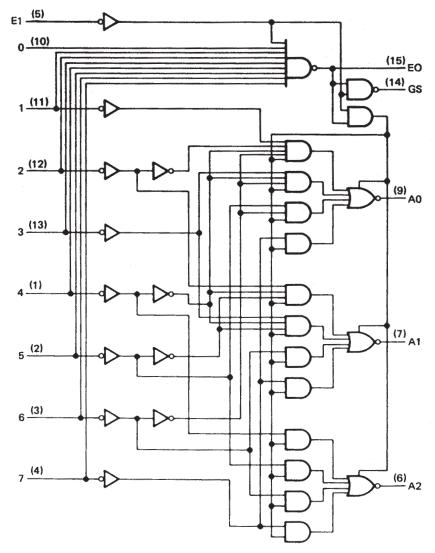
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



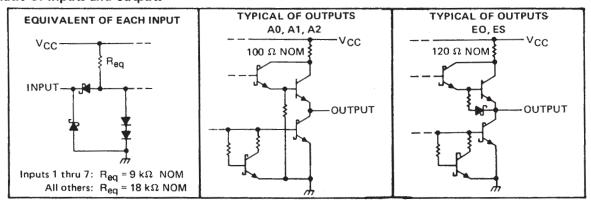
Z = high-impedance state

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematic of inputs and outputs





SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Operating free-air temperature range	SN54LS348
	SN74LS348
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS348			SN74LS348			
		MIN	NOM	MAX	MIN	NOM	MAX	TINU
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5,25	V
High-level output current, IOH	A0, A1, A2			-1			-2.6	mA
mightever or that carrents TOH	EO, GS			-400			-400	μА
Low-level output current, IOI	A0, A1, A2			12			24	mA
Fow-level on that carrent, 10L	EO, GS			4			8	mA
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CO	SN54LS348			SN74LS348			UNIT	
	TAKAMETEN		TEST COI	MIN	TYP‡	MAX	MIN	TYP‡	MAX	ONT	
VIH	High-level input voltage			2			2			V	
V ₁ L Low-level input voltage						**	0.7			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	I ₁ = -18 mA			-1.5			-1.5	V
v _{OH}	High-level	A0, A1, A2	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = -1 mA	2.4	3.1		2,4	3.1		v
· OH	output voltage	EO, GS		$I_{OH} = -2.6 \text{ mA}$ $I_{OH} = -400 \mu\text{A}$	2.5	3.4		2.7	3.4		ľ
V _{OL}		A0, A1, A2	V _{CC} = MIN,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	٧
	Low-level	,,,,,,,	V _{IH} = 2 V,	OL = 24 mA			_		0.35	0.5	
	Output voltage	EO, GS	VIL = VILmax	1 _{OL} = 4 mA		0.25	0.4		0.25	0.4	
			ALE ALEMAX	I _{OL} = 8 mA					0.35	0.5	
loz	Off-State (high-impedance	A0, A1, A2	$V_{CC} = MAX$,	V _O = 2.7 V			20			20	μА
- UZ	state) output current	,,,,,,	V _{IH} = 2 V	V _O = 0.4 V			-20			-20	μΑ
ł _I	Input current at maximum	Inputs 1 thru 7	V _{CC} = MAX,	V. ~ 7 V			0.2			0.2	
-1	input voltage	All other inputs	VCC - MAX,	V - / V			0.1			0.1	mA
Ιн	High-level input current	Inputs 1 thru 7	V _{CC} = MAX,	V 27V			40			40	
30	gir tovor tripat carrent	All other inputs	ACC - MAY	V - 2.7 V			20			20	μA
HL	Low-level input current	Inputs 1 thru 7	V _{CC} = MAX,	V. = 0.4.V			-0.8			-0.8	
11	=500 lover input current	All other inputs	ACC = MYY	V - 0.4 V		,	-0.4			-0.4	mA
los	Short-circuit output current §	Outputs A0, A1, A2	V _{CC} = MAX		-30		-130	-30		-130	
		Outputs EO, GS	VCC - MAX		-20		-100	-20		-100	mA
Icc	Supply current		V _{CC} = MAX,	Condition 1		13	25		13	25	
			See Note 2	Condition 2		12	23		12	. 23	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC (condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open. ICC (condition 2) is measured with all inputs and outputs open.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}$ C.

[§]Not more than one output should be shorted at a time.

SDLS161 - OCTOBER 1976 - REVISED MARCH 1988

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

PARAMETER [†]	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ФLН	1 thru 7	1 thru 7 A0, A1, or A2 In-phase			111	11	17	ns
tPHL.	1 11114 /	A0, A1, 01 A2	output	C. = 45 = 5	2	20	30	113
ФLН	1 shau 7	1 thru 7 A0, A1, or A2 Out-of-phase output CL = 45 pF, RL = 667 Ω, See Note 3				23	35	ns
tPHL	i thru /				23	35	113	
tPZH	EI				25	39	39 ns	
ΨZL] '	70, 71, 01 72				24	41] ""
tPLH	0 thru 7	EO	Out-of-phase			11	18	ns
tPHL	O and /	20	output			26	40	
tPLH	0 thru 7	GS	In-phase	C _L = 15 pF R _L = 2 kΩ,		38	55	ns
tPHL	O and /		output			9	21	1 ""
tPLH	EI	GS	In-phase	See Note 3		11	36 n	
tPHL	1 -	43	output	See Note S		14		ns
ФLН	EI	EO	In-phase			17		
tPHL	1 "		output	:		25	40	ns
tPHZ	EI	A0, A1, or A2		CL = 5 pF		18	27	
ヤLZ] -'	70, 71, 01 72		R _L = 667 Ω		23	35	ns

[†] tpLH = propagation delay time, low-to-high-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

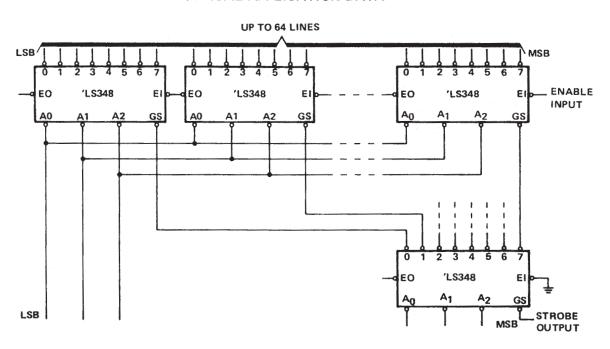


FIGURE 1-PRIORITY ENCODER WITH UP TO 64 INPUTS.



tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level

PACKAGE OPTION ADDENDUM



w.ti.com 6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/36002B2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
JM38510/36002BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS348D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS348NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS348FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS348W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

6-Dec-2006

In no event shall TI's liabil	lity arising out of such inform	ation exceed the total nu	urchase price of the TI pa	art(e) at issue in this do	oument sold by T
to Customer on an annual	lity arising out of such inform I basis.	allon exceed the total po	inchase price of the 11 pa	int(s) at issue in this uc	cument sold by T

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

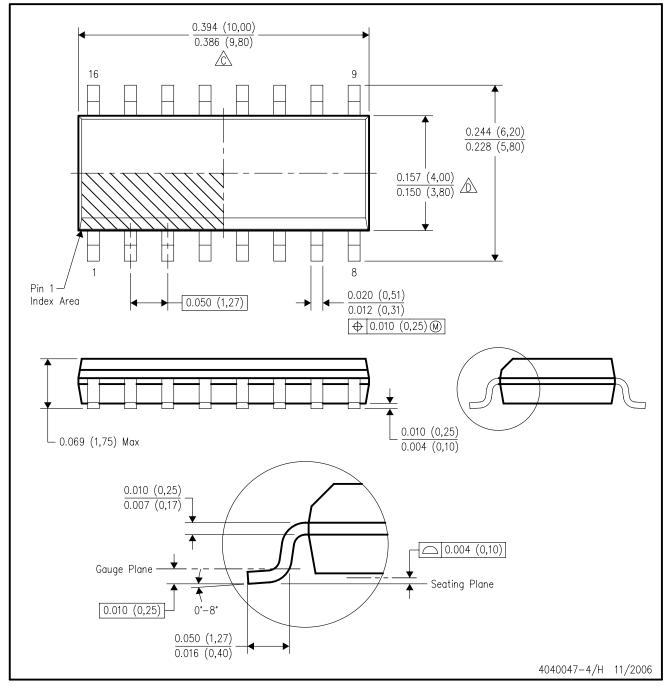


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

	Applications	
amplifier.ti.com	Audio	www.ti.com/audio
dataconverter.ti.com	Automotive	www.ti.com/automotive
dsp.ti.com	Broadband	www.ti.com/broadband
interface.ti.com	Digital Control	www.ti.com/digitalcontrol
logic.ti.com	Military	www.ti.com/military
power.ti.com	Optical Networking	www.ti.com/opticalnetwork
microcontroller.ti.com	Security	www.ti.com/security
www.ti.com/lpw	Telephony	www.ti.com/telephony
	Video & Imaging	www.ti.com/video
	Wireless	www.ti.com/wireless
	dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com	amplifier.ti.com dataconverter.ti.com dsp.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com www.ti.com/lpw Audio Automotive Broadband Digital Control Military Optical Networking Security Telephony Video & Imaging

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated